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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	DMA, LCD, POR, PWM, WDT
Number of I/O	57
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f968-a-gqr

List of Figures

Table 3.1. Pin Definitions for the C8051F96x (Continued)

Name	Pin Numbers			Type	Description
	DQFN76	TQFP80	QFN40		
P0.6 CNVSTR	A38	76	38	D I/O or A In D In	Port 0.6. See Port I/O Section for a complete description. External Convert Start Input for ADC0. See ADC0 section for a complete description.
P0.7 IREF0	A37	74	37	D I/O or A In A Out	Port 0.7. See Port I/O Section for a complete description. IREF0 Output. See IREF Section for complete description.
P1.0 PC0	A36	72	36	D I/O or A In D I/O	Port 1.0. See Port I/O Section for a complete description. Pulse Counter 0.
P1.1 PC1	A35	70	35	D I/O or A In D I/O	Port 1.1. See Port I/O Section for a complete description. Pulse Counter 1.
P1.2 XTAL3	A34	67	34	D I/O or A In A In	Port 1.2. See Port I/O Section for a complete description. SmaRTClock Oscillator Crystal Input.
P1.3 XTAL4	A33	65	33	D I/O or A In A Out	Port 1.3. See Port I/O Section for a complete description. SmaRTClock Oscillator Crystal Output.
P1.4	A31	60	31	D I/O or A In	Port 1.4. See Port I/O Section for a complete description.
P1.5	A30	57	30	D I/O or A In	Port 1.5. See Port I/O Section for a complete description. VIORF supply.
P1.6	A29	56	29	D I/O or A In	Port 1.6. See Port I/O Section for a complete description. VIORF supply. May also be used as INT0 or INT1.
P1.7	A28	54	28	D I/O or A In	Port 1.7. See Port I/O Section for a complete description. VIORF supply. May also be used as INT0 or INT1.
P2.0	A27	53	27	D I/O or A In	Port 2.0. See Port I/O Section for a complete description. VIORF supply. May also be used as SCK for SPI1.

3.1.2. Land Pattern

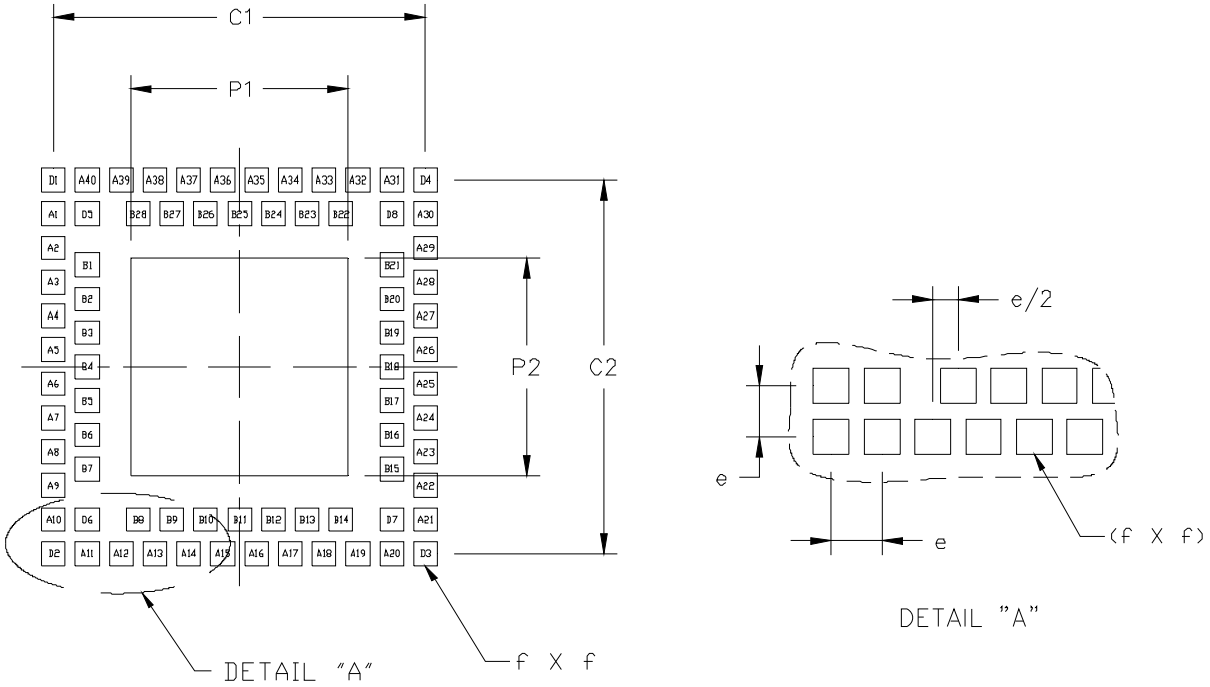

Figure 3.5. DQFN-76 Land Pattern

Table 3.3. DQFN-76 Land Pattern Dimensions

	Dimension (mm)	
Symbol	**Typ**	**Max**
C1	5.50	—
C2	5.50	—
e	0.50	—
f	—	0.35
P1	—	3.20
P2	—	3.20

Notes:

1. All feature sizes shown are at Maximum Material Condition (MMC) and a card fabrication tolerance of 0.05 mm is assumed.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.

4. Electrical Characteristics

Throughout the Electrical Characteristics chapter:

- "VIO" refers to the VIO or VIORF Supply Voltage.

4.1. Absolute Maximum Specifications

Table 4.1. Absolute Maximum Ratings

Parameter	Condition	Min	Typ	Max	Unit
Ambient Temperature under Bias		–55	—	125	°C
Storage Temperature		–65	—	150	°C
Voltage on any VIO Port I/O Pin (all Port I/O pins except P1.5/6/7 and P2.0/1/2/3) or $\overline{\text{RST}}$ with respect to GND		–0.3	—	VIO + 2	V
Voltage on P1.5/6/7 or P2.0/1/2/3 with respect to GND.		–0.3	—	VIORF + 2	V
Voltage on VBAT, VBATDC, VIO, or VIORF with respect to GND		–0.3	—	4.0	V
Maximum Total Current through VBAT or GND		—	—	500	mA
Maximum Current through $\overline{\text{RST}}$ or any Port Pin		—	—	100	mA
Maximum Total Current through all Port Pins		—	—	200	mA

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

4.2. Electrical Characteristics

Table 4.2. Global Electrical Characteristics

–40 to +85 °C, 25 MHz system clock unless otherwise specified.

Parameter	Condition	Min	Typ	Max	Unit
Supply Voltage (V_{BAT})		1.8		3.8	V
Minimum RAM Data Retention Voltage[1]	Not in sleep mode in sleep mode	— —	1.4 0.3	— 0.5	V
SYSCLK (System Clock)[2]		0	—	25	MHz
T_{SYSH} (SYSCLK High Time)		18	—	—	ns
T_{SYSL} (SYSCLK Low Time)		18	—	—	ns
Specified Operating Temperature Range		–40	—	+85	°C

Notes:

1. Based on device characterization data; Not production tested.
2. SYSCLK must be at least 32 kHz to enable debugging.

Table 4.3. Digital Supply Current at VBAT pin with DC-DC Converter Enabled

–40 to +85 °C, VBAT = 3.6V, VDC = 1.9 V, 24.5 MHz system clock unless otherwise specified.

Parameter	Condition	Min	Typ	Max	Unit
Digital Supply Current—CPU Active (Normal Mode, fetching instructions from flash, no external load)					
I_{BAT} [1,2,3]	V_{BAT}= 3.0 V	—	4.1	—	mA
	V_{BAT}= 3.3 V	—	4.0	—	mA
	V_{BAT}= 3.6 V	—	3.8	—	mA
Digital Supply Current—CPU Inactive (Sleep Mode, sourcing current to external device)					
I_{BAT}[1]	sourcing 9 mA to external device	—	6.5	—	mA
	sourcing 19 mA to external device	—	13	—	mA

Notes:

1. Based on device characterization data; Not production tested.
2. Digital Supply Current depends upon the particular code being executed. The values in this table are obtained with the CPU executing a mix of instructions in two loops: djnz R1, $, followed by a loop that accesses an SFR, and moves data around using the CPU (between accumulator and b-register). The supply current will vary slightly based on the physical location of this code in flash. As described in the Flash Memory chapter, it is best to align the jump addresses with a flash word address (byte location /4), to minimize flash accesses and power consumption.
3. Includes oscillator and regulator supply current.

Table 4.16. Comparator Electrical Characteristics

V_{BAT} = 1.8 to 3.8 V, –40 to +85 °C unless otherwise noted.

Parameter	Conditions	Min	Typ	Max	Units
Response Time: Mode 0, V_{BAT} = 2.4 V, V_{CM}* = 1.2 V	CP0+ – CP0– = 100 mV	—	120	—	ns
	CP0+ – CP0– = –100 mV	—	110	—	ns
Response Time: Mode 1, V_{BAT} = 2.4 V, V_{CM}* = 1.2 V	CP0+ – CP0– = 100 mV	—	180	—	ns
	CP0+ – CP0– = –100 mV	—	220	—	ns
Response Time: Mode 2, V_{BAT} = 2.4 V, V_{CM}* = 1.2 V	CP0+ – CP0– = 100 mV	—	350	—	ns
	CP0+ – CP0– = –100 mV	—	600	—	ns
Response Time: Mode 3, V_{BAT} = 2.4 V, V_{CM}* = 1.2 V	CP0+ – CP0– = 100 mV	—	1240	—	ns
	CP0+ – CP0– = –100 mV	—	3200	—	ns
Common-Mode Rejection Ratio		—	1.5	—	mV/V
Inverting or Non-Inverting Input Voltage Range		–0.25	—	V_{BAT} + 0.25	V
Input Capacitance		—	12	—	pF
Input Bias Current		—	1	—	nA
Input Offset Voltage		–10	—	+10	mV
Power Supply					
Power Supply Rejection		—	0.1	—	mV/V
Power-up Time	V_{BAT} = 3.8 V	—	0.6	—	µs
	V_{BAT} = 3.0 V	—	1.0	—	µs
	V_{BAT} = 2.4 V	—	1.8	—	µs
	V_{BAT} = 1.8 V	—	10	—	µs
Supply Current at DC	Mode 0	—	23	—	µA
	Mode 1	—	8.8	—	µA
	Mode 2	—	2.6	—	µA
	Mode 3	—	0.4	—	µA

***Note:** Vcm is the common-mode voltage on CP0+ and CP0–.

7.2. Comparator Outputs

When a comparator is enabled, its output is a logic 1 if the voltage at the positive input is higher than the voltage at the negative input. When disabled, the comparator output is a logic 0. The comparator output is synchronized with the system clock as shown in Figure 7.2. The synchronous “latched” output (CP0, CP1) can be polled in software (CPnOUT bit), used as an interrupt source, or routed to a Port pin through the Crossbar.

The asynchronous “raw” comparator output (CP0A, CP1A) is used by the low power mode wakeup logic and reset decision logic. See the Power Options chapter and the Reset Sources chapter for more details on how the asynchronous comparator outputs are used to make wake-up and reset decisions. The asynchronous comparator output can also be routed directly to a Port pin through the Crossbar, and is available for use outside the device even if the system clock is stopped.

When using a Comparator as an interrupt source, Comparator interrupts can be generated on rising-edge and/or falling-edge comparator output transitions. Two independent interrupt flags (CPnRIF and CPnFIF) allow software to determine which edge caused the Comparator interrupt. The comparator rising-edge and falling-edge interrupt flags are set by hardware when a corresponding edge is detected regardless of the interrupt enable state. Once set, these bits remain set until cleared by software.

The rising-edge and falling-edge interrupts can be individually enabled using the CPnRIE and CPnFIE interrupt enable bits in the CPTnMD register. In order for the CPnRIF and/or CPnFIF interrupt flags to generate an interrupt request to the CPU, the Comparator must be enabled as an interrupt source and global interrupts must be enabled. See the Interrupt Handler chapter for additional information.

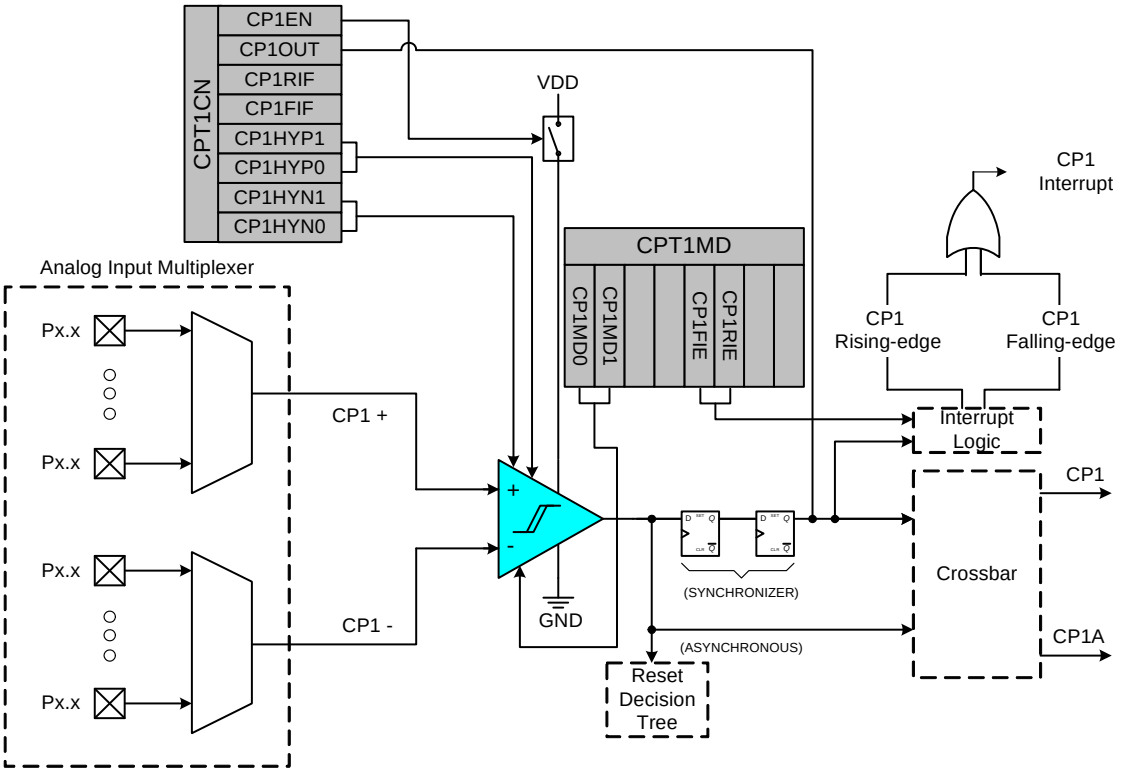

Figure 7.2. Comparator 1 Functional Block Diagram

SFR Definition 7.6. CPT1MX: Comparator1 Input Channel Select

Bit	7	6	5	4	3	2	1	0
Name	CMX1N[3:0]				CMX1P[3:0]			
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	1	1	1	1	1	1	1	1

SFR Page = 0x0; SFR Address = 0x9E

Bit	Name	Function			
7:4	CMX1N	**Comparator1 Negative Input Selection.** Selects the negative input channel for Comparator1.			
		0000:	P0.1	1000:	P2.1
		0001:	P0.3	1001:	P2.3
		0010:	P0.5	1010:	Reserved
		0011:	Reserved	1011:	Reserved
		0100:	Reserved	1100:	Compare
		0101:	Reserved	1101:	VBAT divided by 2
		0110:	P1.5	1110:	Digital Supply Voltage
		0111:	P1.7	1111:	Ground
3:0	CMX1P	**Comparator1 Positive Input Selection.** Selects the positive input channel for Comparator1.			
		0000:	P0.0	1000:	P2.0
		0001:	P0.2	1001:	P2.2
		0010:	P0.4	1010:	Reserved
		0011:	P0.6	1011:	Reserved
		0100:	Reserved	1100:	Compare
		0101:	Reserved	1101:	VBAT divided by 2
		0110:	P1.4	1110:	VBAT Supply Voltage
		0111:	P1.6	1111:	VDC Supply Voltage

SFR Definition 8.3. SP: Stack Pointer

Bit	7	6	5	4	3	2	1	0
Name	SP[7:0]							
Type	R/W							
Reset	0	0	0	0	0	1	1	1

SFR Page = All Pages; SFR Address = 0x81

Bit	Name	Function
7:0	SP[7:0]	**Stack Pointer.** The Stack Pointer holds the location of the top of the stack. The stack pointer is incremented before every PUSH operation. The SP register defaults to 0x07 after reset.

SFR Definition 8.4. ACC: Accumulator

Bit	7	6	5	4	3	2	1	0
Name	ACC[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = All Pages; SFR Address = 0xE0; Bit-Addressable

Bit	Name	Function
7:0	ACC[7:0]	**Accumulator.** This register is the accumulator for arithmetic operations.

SFR Definition 8.5. B: B Register

Bit	7	6	5	4	3	2	1	0
Name	B[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = All Pages; SFR Address = 0xF0; Bit-Addressable

Bit	Name	Function
7:0	B[7:0]	**B Register.** This register serves as a second accumulator for certain arithmetic operations.

12.2. 32-bit CRC Algorithm

The C8051F41x CRC unit calculates the 32-bit CRC using a poly of 0x04C11DB7. The CRC-32 algorithm is "reflected", meaning that all of the input bytes and the final 32-bit output are bit-reversed in the processing engine. The following is a description of a simplified CRC algorithm that produces results identical to the hardware:

Step 1. XOR the least-significant byte of the current CRC result with the input byte. If this is the first iteration of the CRC unit, the current CRC result will be the set initial value (0x00000000 or 0xFFFFFFFF).
Step 2. Right-shift the CRC result.
Step 3. If the LSB of the CRC result is set, XOR the CRC result with the reflected polynomial (0xEDB88320).
Step 4. Repeat at Step 2 for the number of input bits (8).

For example, the 32-bit 'F41x CRC algorithm can be described by the following code:

```
unsigned long UpdateCRC (unsigned long CRC_acc, unsigned char CRC_input)
{
   unsigned char i; // loop counter
   #define POLY 0xEDB88320 // bit-reversed version of the poly 0x04C11DB7
   // Create the CRC "dividend" for polynomial arithmetic (binary arithmetic
   // with no carries)

   CRC_acc = CRC_acc ^ CRC_input;

   // "Divide" the poly into the dividend using CRC XOR subtraction
   // CRC_acc holds the "remainder" of each divide
   //
   // Only complete this division for 8 bits since input is 1 byte
   for (i = 0; i < 8; i++)
   {
      // Check if the MSB is set (if MSB is 1, then the POLY can "divide"
      // into the "dividend")
      if ((CRC_acc & 0x00000001) == 0x00000001)
      {
         // if so, shift the CRC value, and XOR "subtract" the poly
         CRC_acc = CRC_acc >> 1;
         CRC_acc ^= POLY;
      }
      else
      {
         // if not, just shift the CRC value
         CRC_acc = CRC_acc >> 1;
      }
   }
   // Return the final remainder (CRC value)
   return CRC_acc;
}
```

The following table lists several input values and the associated outputs using the 32-bit 'F41x CRC algorithm (an initial value of 0xFFFFFFFF is used):

SFR Definition 12.2. CRC0IN: CRC0 Data Input

Bit	7	6	5	4	3	2	1	0
Name	CRC0IN[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0xF; SFR Address = 0x93

Bit	Name	Function
7:0	CRC0IN[7:0]	**CRC0 Data Input.** Each write to CRC0IN results in the written data being computed into the existing CRC result according to the CRC algorithm described in Section 12.1

SFR Definition 12.3. CRC0DAT: CRC0 Data Output

Bit	7	6	5	4	3	2	1	0
Name	CRC0DAT[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0xF; SFR Address = 0x91

Bit	Name	Function
7:0	CRC0DAT[7:0]	**CRC0 Data Output.** Each read or write performed on CRC0DAT targets the CRC result bits pointed to by the CRC0 Result Pointer (CRC0PNT bits in CRC0CN).

SFR Definition 24.1. RTC0KEY: SmaRTClock Lock and Key

Bit	7	6	5	4	3	2	1	0
Name	RTC0ST[7:0]							
Type	R/W							
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xAE

Bit	Name	Function
7:0	RTC0ST	**SmaRTClock Interface Status.** Provides lock status when read. **Read:** **0x02:** SmaRTClock Interface is unlocked. **Write:** Writes to RTC0KEY have no effect.

SFR Definition 24.2. RTC0ADR: SmaRTClock Address

Bit	7	6	5	4	3	2	1	0
Name		AUTORD		ADDR[4:0]				
Type	R	R/W	R	R/W				
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xAC

Bit	Name	Function
7	Reserved	Read = 0; Write = don't care.
6	AUTORD	**SmaRTClock Interface Autoread Enable.** Enables/disables Autoread. 0: Autoread Disabled. 1: Autoread Enabled.
5	Unused	Read = 0b; Write = Don't Care.
4:0	ADDR[4:0]	**SmaRTClock Indirect Register Address.** Sets the currently selected SmaRTClock register. See Table 24.1 for a listing of all SmaRTClock indirect registers.
Note: The ADDR bits increment after each indirect read/write operation that targets a CAPTUREn or ALARMnBn internal SmaRTClock register.		

running (RTC0TR = 1) in order to set or capture the main timer. The transfer can take up to 2 smaRTClock cycles to complete.

24.3.2. Setting a SmaRTClock Alarm

The SmaRTClock alarm function compares the 32-bit value of SmaRTClock Timer to the value of the ALARMnBn registers. An alarm event is triggered if the SmaRTClock timer is **equal to** the ALARMnBn registers. If Auto Reset is enabled, the 32-bit timer will be cleared to zero one SmaRTClock cycle after the alarm 0 event.

The SmaRTClock alarm event can be configured to reset the MCU, wake it up from a low power mode, or generate an interrupt. See Section “17. Interrupt Handler” on page 232, Section “19. Power Management” on page 257, and Section “22. Reset Sources” on page 278 for more information.

The following steps can be used to set up a SmaRTClock Alarm:

1. Disable SmaRTClock Alarm Events (RTC0AEN = 0).
2. Set the ALARMn registers to the desired value.
3. Enable SmaRTClock Alarm Events (RTC0AEN = 1).

Notes:

1. The ALRM bit, which is used as the SmaRTClock Alarm Event flag, is cleared by disabling SmaRTClock Alarm Events (RTC0AEN = 0).
2. If AutoReset is disabled, disabling (RTC0AEN = 0) then Re-enabling Alarm Events (RTC0AEN = 1) after a SmaRTClock Alarm without modifying ALARMn registers will automatically schedule the next alarm after 2^32 SmaRTClock cycles (approximately 36 hours using a 32.768 kHz crystal).

24.3.3. Software Considerations for using the SmaRTClock Timer and Alarm

The SmaRTClock timer and alarm have two operating modes to suit varying applications. The two modes are described below:

Mode 1:
The first mode uses the SmaRTClock timer as a perpetual timebase which is never reset to zero. Every 36 hours, the timer is allowed to overflow without being stopped or disrupted. The alarm interval is software managed and is added to the ALRMnBn registers by software after each alarm. This allows the alarm match value to always stay ahead of the timer by one software managed interval. If software uses 32-bit unsigned addition to increment the alarm match value, then it does not need to handle overflows since both the timer and the alarm match value will overflow in the same manner.

This mode is ideal for applications which have a long alarm interval (e.g., 24 or 36 hours) and/or have a need for a perpetual timebase. An example of an application that needs a perpetual timebase is one whose wake-up interval is constantly changing. For these applications, software can keep track of the number of timer overflows in a 16-bit variable, extending the 32-bit (36 hour) timer to a 48-bit (272 year) perpetual timebase.

Mode 2:
The second mode uses the SmaRTClock timer as a general purpose up counter which is auto reset to zero by hardware after each alarm 0 event. The alarm interval is managed by hardware and stored in the ALRM0Bn registers. Software only needs to set the alarm interval once during device initialization. After each alarm 0 event, software should keep a count of the number of alarms that have occurred in order to keep track of time. Alarm 1 and alarm 2 events do not trigger the auto reset.

This mode is ideal for applications that require minimal software intervention and/or have a fixed alarm interval. This mode is the most power efficient since it requires less CPU time per alarm.

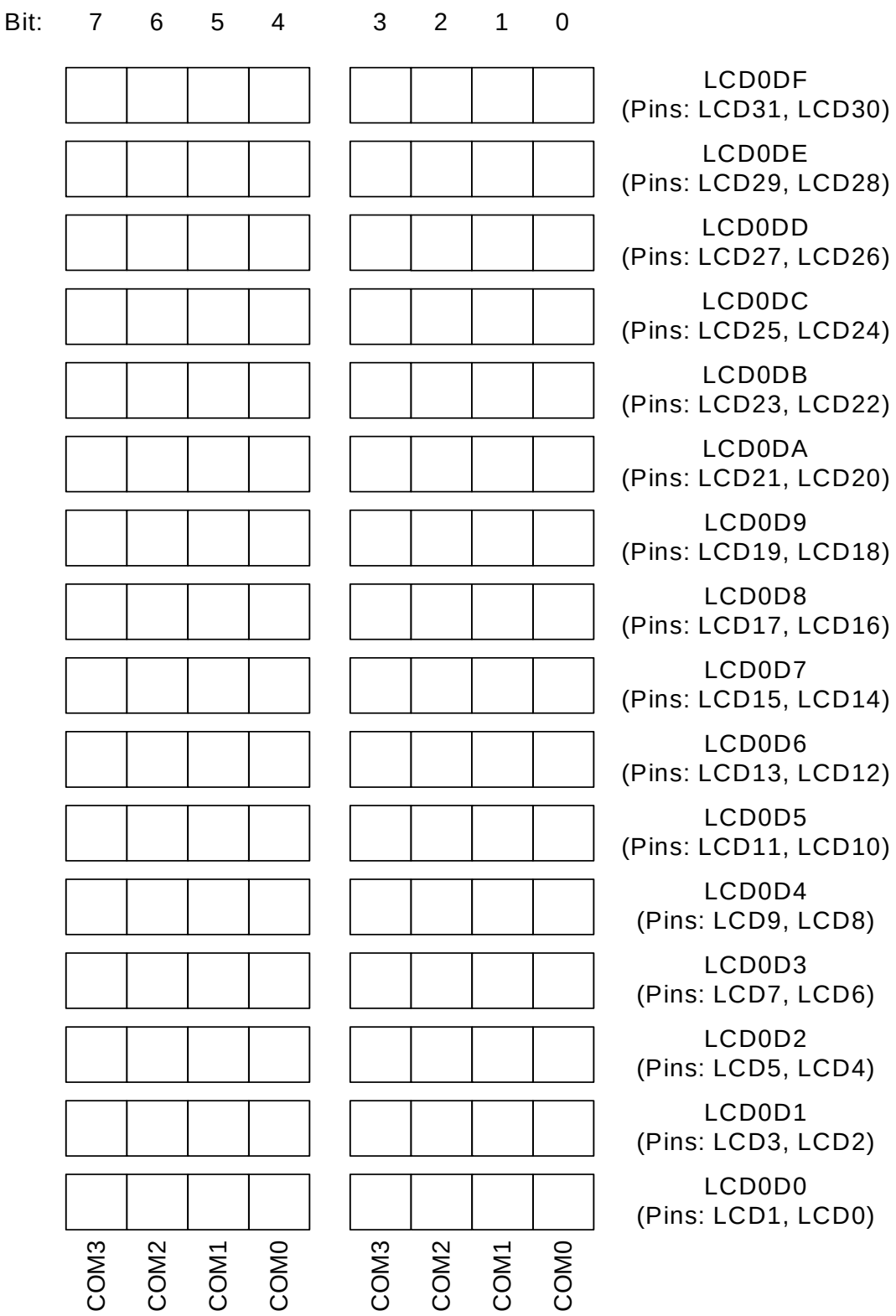

Figure 26.2. LCD Data Register to LCD Pin Mapping

All transactions are initiated by a master, with one or more addressed slave devices as the target. The master generates the START condition and then transmits the slave address and direction bit. If the transaction is a WRITE operation from the master to the slave, the master transmits the data a byte at a time waiting for an ACK from the slave at the end of each byte. For READ operations, the slave transmits the data waiting for an ACK from the master at the end of each byte. At the end of the data transfer, the master generates a STOP condition to terminate the transaction and free the bus. Figure 28.3 illustrates a typical SMBus transaction.

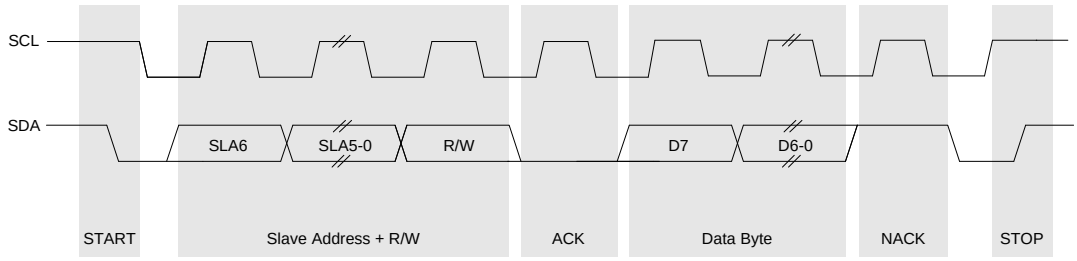

Figure 28.3. SMBus Transaction

28.3.1. Transmitter Vs. Receiver

On the SMBus communications interface, a device is the “transmitter” when it is sending an address or data byte to another device on the bus. A device is a “receiver” when an address or data byte is being sent to it from another device on the bus. The transmitter controls the SDA line during the address or data byte. After each byte of address or data information is sent by the transmitter, the receiver sends an ACK or NACK bit during the ACK phase of the transfer, during which time the receiver controls the SDA line.

28.3.2. Arbitration

A master may start a transfer only if the bus is free. The bus is free after a STOP condition or after the SCL and SDA lines remain high for a specified time (see Section “28.3.5. SCL High (SMBus Free) Timeout” on page 384). In the event that two or more devices attempt to begin a transfer at the same time, an arbitration scheme is employed to force one master to give up the bus. The master devices continue transmitting until one attempts a HIGH while the other transmits a LOW. Since the bus is open-drain, the bus will be pulled LOW. The master attempting the HIGH will detect a LOW SDA and lose the arbitration. The winning master continues its transmission without interruption; the losing master becomes a slave and receives the rest of the transfer if addressed. This arbitration scheme is non-destructive: one device always wins, and no data is lost.

28.3.3. Clock Low Extension

SMBus provides a clock synchronization mechanism, similar to I^2C, which allows devices with different speed capabilities to coexist on the bus. A clock-low extension is used during a transfer in order to allow slower slave devices to communicate with faster masters. The slave may temporarily hold the SCL line LOW to extend the clock low period, effectively decreasing the serial clock frequency.

28.3.4. SCL Low Timeout

If the SCL line is held low by a slave device on the bus, no further communication is possible. Furthermore, the master cannot force the SCL line high to correct the error condition. To solve this problem, the SMBus protocol specifies that devices participating in a transfer must detect any clock cycle held low longer than 25 ms as a “timeout” condition. Devices that have detected the timeout condition must reset the communication no later than 10 ms after detecting the timeout condition.

When the SMBTOE bit in SMB0CF is set, Timer 3 is used to detect SCL low timeouts. Timer 3 is forced to reload when SCL is high, and allowed to count when SCL is low. With Timer 3 enabled and configured to

Table 28.1. SMBus Clock Source Selection

SMBCS1	SMBCS0	SMBus Clock Source
0	0	Timer 0 Overflow
0	1	Timer 1 Overflow
1	0	Timer 2 High Byte Overflow
1	1	Timer 2 Low Byte Overflow

The SMBCS1–0 bits select the SMBus clock source, which is used only when operating as a master or when the Free Timeout detection is enabled. When operating as a master, overflows from the selected source determine the absolute minimum SCL low and high times as defined in Equation 28.1. The selected clock source may be shared by other peripherals so long as the timer is left running at all times. For example, Timer 1 overflows may generate the SMBus and UART baud rates simultaneously. Timer configuration is covered in Section “32. Timers” on page 444.

$$T_{HighMin} = T_{LowMin} = \frac{1}{f_{ClockSourceOverflow}}$$

Equation 28.1. Minimum SCL High and Low Times

The selected clock source should be configured to establish the minimum SCL High and Low times as per Equation 28.1. When the interface is operating as a master (and SCL is not driven or extended by any other devices on the bus), the typical SMBus bit rate is approximated by Equation 28.1.

$$BitRate = \frac{f_{ClockSourceOverflow}}{3}$$

Equation 28.2. Typical SMBus Bit Rate

Figure 28.4 shows the typical SCL generation described by Equation 28.2. Notice that T_{HIGH} is typically twice as large as T_{LOW}. The actual SCL output may vary due to other devices on the bus (SCL may be extended low by slower slave devices, or driven low by contending master devices). The bit rate when operating as a master will never exceed the limits defined by Equation 28.2.

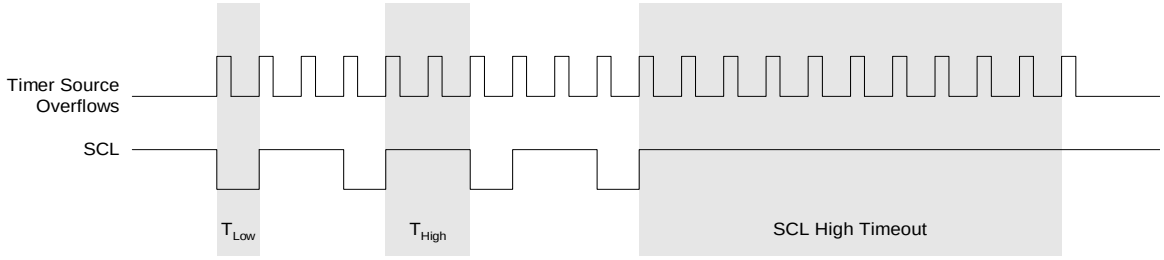

Figure 28.4. Typical SMBus SCL Generation

Setting the EXTHOLD bit extends the minimum setup and hold times for the SDA line. The minimum SDA setup time defines the absolute minimum time that SDA is stable before SCL transitions from low-to-high. The minimum SDA hold time defines the absolute minimum time that the current SDA value remains stable after SCL transitions from high-to-low. EXTHOLD should be set so that the minimum setup and hold times meet the SMBus Specification requirements of 250 ns and 300 ns, respectively. Table 28.2 shows the minimum setup and hold times for the two EXTHOLD settings. Setup and hold time extensions are typically necessary when SYSCLK is above 10 MHz.

Table 29.2. Timer Settings for Standard Baud Rates Using an External 22.1184 MHz Oscillator

	Frequency: 22.1184 MHz						
	Target Baud Rate (bps)	Baud Rate % Error	Oscillator Divide Factor	Timer Clock Source	SCA1–SCA0 (pre-scale select)[1]	T1M[1]	Timer 1 Reload Value (hex)
SYSCLK from Internal Osc.	230400	0.00%	96	EXTCLK / 8	11	0	0xFA
	115200	0.00%	192	EXTCLK / 8	11	0	0xF4
	57600	0.00%	384	EXTCLK / 8	11	0	0xE8
	28800	0.00%	768	EXTCLK / 8	11	0	0xD0
	14400	0.00%	1536	EXTCLK / 8	11	0	0xA0
	9600	0.00%	2304	EXTCLK / 8	11	0	0x70

Notes:
1. SCA1–SCA0 and T1M bit definitions can be found in Section 32.1.
2. X = Don't care.

SFR Definition 32.8. TMR2CN: Timer 2 Control

Bit	7	6	5	4	3	2	1	0
Name	TF2H	TF2L	TF2LEN	TF2CEN	T2SPLIT	TR2	T2XCLK[1:0]	
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0xC8; Bit-Addressable

Bit	Name	Function
7	TF2H	**Timer 2 High Byte Overflow Flag.** Set by hardware when the Timer 2 high byte overflows from 0xFF to 0x00. In 16 bit mode, this will occur when Timer 2 overflows from 0xFFFF to 0x0000. When the Timer 2 interrupt is enabled, setting this bit causes the CPU to vector to the Timer 2 interrupt service routine. This bit is not automatically cleared by hardware.
6	TF2L	**Timer 2 Low Byte Overflow Flag.** Set by hardware when the Timer 2 low byte overflows from 0xFF to 0x00. TF2L will be set when the low byte overflows regardless of the Timer 2 mode. This bit is not automatically cleared by hardware.
5	TF2LEN	**Timer 2 Low Byte Interrupt Enable.** When set to 1, this bit enables Timer 2 Low Byte interrupts. If Timer 2 interrupts are also enabled, an interrupt will be generated when the low byte of Timer 2 overflows.
4	TF2CEN	**Timer 2 Capture Enable.** When set to 1, this bit enables Timer 2 Capture Mode.
3	T2SPLIT	**Timer 2 Split Mode Enable.** When set to 1, Timer 2 operates as two 8-bit timers with auto-reload. Otherwise, Timer 2 operates in 16-bit auto-reload mode.
2	TR2	**Timer 2 Run Control.** Timer 2 is enabled by setting this bit to 1. In 8-bit mode, this bit enables/disables TMR2H only; TMR2L is always enabled in split mode.
1:0	T2XCLK[1:0]	**Timer 2 External Clock Select.** This bit selects the “external” and “capture trigger” clock sources for Timer 2. If Timer 2 is in 8-bit mode, this bit selects the “external” clock source for both timer bytes. Timer 2 Clock Select bits (T2MH and T2ML in register CKCON) may still be used to select between the “external” clock and the system clock for either timer. Note: External clock sources are synchronized with the system clock. 00: External Clock is SYSCLK/12. Capture trigger is SmaRTClock/8. 01: External Clock is Comparator 0. Capture trigger is SmaRTClock/8. 10: External Clock is SYSCLK/12. Capture trigger is Comparator 0. 11: External Clock is SmaRTClock/8. Capture trigger is Comparator 0.

Table 33.3. Watchdog Timer Timeout Intervals[1]

System Clock (Hz)	PCA0CPL5	Timeout Interval (ms)
24,500,000	255	32.1
24,500,000	128	16.2
24,500,000	32	4.1
3,062,500[2]	255	257
3,062,500[2]	128	129.5
3,062,500[2]	32	33.1
32,000	255	24576
32,000	128	12384
32,000	32	3168

Notes:
1. Assumes SYSCLK/12 as the PCA clock source, and a PCA0L value of 0x00 at the update time.
2. Internal SYSCLK reset frequency = Internal Oscillator divided by 8.